IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

| In re Patent Application of |) Attorney Docket No.: SUGI0064 |
|--------------------------------|---------------------------------|
| •• |) Confirmation No.: 7328 |
| Tadahiro OHMI et al. |) |
| |) Group Art Unit: 1764 |
| Serial No.: 09/773,605 |) |
| |) Examiner: Jennifer A. LEUNG |
| Filed: February 2, 2001 |) |
| |) |
| For: APPARATUS AND REACTOR FOR | .) |
| GENERATING AND FEEDING HIC | 6H) |
| PURITY MOISTURE |) |

DECLARATION UNDER RULE 132

MAIL STOP: AF

U.S. Patent and Trademark Office Customer Service Window Randolph Building 401 Dulany Street Alexandria, VA 22314

Sir:

- I, Keiichi Hasegawa, state that I am an expert in the field of Mechanical Engineering.
 Specifically, I am the chief at Fujikin Incorporated, Osaka High-Tech Research Institute in Osaka Japan.
- I am familiar with the above-captioned application, including the drawings. I
 understand that the Examiner has rejected certain of the amendments to the claims as
 not supported by the drawings.
- 3. I expect that a person reviewing Fig. 6 originally filed in the present application would understand it to describe a reflector plate having a thickness exceeding one half of the distance between the supply passage and the outlet passage.

杉本丈夫特許事務所

Fax: 06-6201-5509

2006年 1月30日(月) 14:24

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Patent Application Serial No. 09/773,605 Attorney Docket No. SUGI0064

4. I further expect that a person would understand that the "thickness" of the reflector plate would refer to the thickness at the central portion, and not the thickness at the peripheral edge.

5. I declare under penalty of perjury that the foregoing is true and correct, that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Signed by,

Date: ____ January 27, 2006

Keiichi Hasegawa

[INSERT NAME]